



**PACKAGING ADHESIVE/SEALANT RJQ49
FORMULATION 7326**

RJQ49 7326 is a B-staged adhesive/sealant for sealing electronic packages. It is ideal for use in automated sealing applications. Formula 7326 has lower chloride content and high performance as adhesive for ceramic and gold plated metal substrates.

TYPICAL PROPERTIES

Max operating temperature (continuous), °C	160
Outgassing	NA
Moisture absorption (24 hr. soak in water @ 100°C)	<2.0%
Total ionic content (specific electrical conductance), mS/m	< 4.5
Extractable Ions, ppm	NA
Hydrolysable chloride content, ppm (MIL-STD 883H Method 5011.5)	< 50
Tg by DSC, °C	98
Modulus, psi	NA
CTE, ppm/°C	70
Dielectric constant (@ 1MHz)	3.3
Volume resistivity, Ohm-cm	3.5×10^{16}
Thermal conductivity, W/m-k	0.3 – 0.4

TYPICAL SEALED PACKAGE PERFORMANCE PROPERTIES*

Reflow temperature, °C	260
Lap shear strength (gold/ceramic @ 25°C), psi	3200

*These values may vary depending upon the materials to which the epoxy is adhered. All above data is based on sealed packages consisting of a ceramic header and a ceramic lid.

SEALING AND CURING

The recommended curing cycles for clip-bake sealing process is 30 minutes at 120°C followed with 1 hour at 160 - 165°C under 1 - 5 psi of pressure. For alternate curing practices or automatic sealing procedures, please consult RJR Technologies. Customer Service. (Phone 510-638-5901 or Fax 510-638-5958)

STORAGE AND HANDLING

Keep parts with the material in vacuum sealed bag with dry-packs at 3-8°C and <50% RH. Shelf life of the material when stored under refrigerated conditions (3-8°C) is 6 months from the date of manufacture. Room temperature and frozen storage conditions may be appropriate for some applications. Please consult RJR Technologies Customer Service for specific storage options.

REGULATORY

This product is RoHS compliant.

NOTICE

This data is provided for guideline purposes. No warranty is made on the actual use. Customers should perform their own tests and qualifications.